

## Declaration and Power of Attorney for Patent Application

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name: I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: **METHOD AND STRUCTURE FOR COOLING A DUAL CHIP MODULE WITH ONE HIGH POWER CHIP**

the specification of which (check one)



is attached hereto.



was filed on \_\_\_\_\_ as Application Serial No. \_\_\_\_\_ and was amended on \_\_\_\_\_.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

**Prior Foreign Application(s):**

Number	Country	Day/Month/Year	Priority Claimed
--------	---------	----------------	------------------

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose information material to the patentability of this application as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

**Prior U.S. Applications:**

Serial No.	Filing Date	Status
------------	-------------	--------

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

As a named inventor, I hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: Joseph P. Abate (Reg. No. 30,238), Jesse Abzug (Reg. No. 31,316), Jay Anderson (Reg. No. 38,371), Ira D. Blocker (Reg. No. 29,894), Steven Capella (Reg. No. 33,086), H. Daniel Schnurmann (Reg. No. 35,791), Tiffany Townsend, (Reg. No. P-43,199), William P. Skadony (Reg. No. 33,787), Anthony N. Magistrale (Reg. No. 35,595), Harold Huberfeld (Reg. No. 26,665), Todd M.C. Li (Reg. No. 45,554), Margaret A. Pepper (Reg. No. 45,008), Stanley B. Green (Reg. No. 24,351), Christopher A. Hughes (Reg. No. 26,914), John E. Hoel (Reg. No. 26,279), Joseph C. Redmond, Jr. (Reg. No. 18,753), Eugene I. Shkurko (Reg. No. 36,678), Steven Soucar (Reg. No. 32,440), Anthony N. Magistrale (Reg. No. 35,595), Sean M. McGinn (Reg. No. 34, 386), and Frederick W. Gibb, III (Reg. No. 37,629).

Send all correspondence to: Frederick W. Gibb, III  
Registration No. 37,629  
McGinn & Gibb, PLLC  
2568-A Riva Road, Suite 304  
Annapolis, MD 21401

Direct Telephone Calls to: Frederick W. Gibb, III (301) 261-8071

- (1) Inventor: Amlicar R. Avelo  
 Signature: *[Signature]* 09/25/03  
 Residence: 12 Rambling Brook Lane, Poughkeepsie, NY 12601  
 Citizenship: USA  
 Post Office Address: Same as residence.
- 
- (2) Inventor: Kamal Kumar Sikka  
 Signature: *[Signature]* 09/25/2003  
 Residence: 97 Autumn Drive, Poughkeepsie, NY 12603  
 Citizenship: India  
 Post Office Address: Same as residence
- 
- (3) Inventor: Milton T. Toy  
 Signature: *[Signature]* 9/25/03  
 Residence: ~~27 Kendall Drive, Wappingers Falls, NY 12590~~  
 24 Champlain Drive, Hopewell Jn, NY 12533  
 Citizenship: USA  
 Post Office Address: Same as residence
-

Taiwan

Docket No.: FIS920030258

**OATH & ASSIGNMENT**

The undersigned,

- (1) Amilcar R. Arvelo
- (2) Kamal Kumar Sikka
- (3) Hilton T. Toy

citizens of:

United States of America  
India  
United States of America

residing at:

- (1) 12 Rambling Brook Lane, Poughkeepsie, NY 12601
- (2) 97 Autumn Drive, Poughkeepsie, NY 12603
- (3) ~~27 Kendall Drive, Wappingers Falls, NY 12590~~  
24 Champlain Drive, Hopewell Jn, NY 12533

hereby undertake that the invention/new utility mode/new design entitled:

**METHOD AND STRUCTURE FOR COOLING A DUAL CHIP MODULE WITH ONE  
HIGH POWER CHIP**

was truly invented by us. The undersigned agree to accept punishments provided for in laws in case of any imposture, plagiarism, imitation or deceptive activities.

1. The undersigned hereby assigns all its rights and interests regarding the invention as far as the Republic of China is concerned to:

**International Business Machines Corporation**

(hereinafter "Assignee"), a corporation respectfully organized and existing under the laws of New York, United States of America

and located at New Orchard Road, Armonk, New York 10504, United States of America

and do hereby declare that the Assignee is entitled to apply for and obtain patent rights on the invention in its own name in the Republic of China.

Signature(s)



**Amilcar R. Arvelo**

Kamal K. Sikka

**Kamal Kumar Sikka**

Hilton T. Toy

**Hilton T. Toy**

Date

09/25/03

09/25/2003

9/25/03